

a second support plate proximately positioned with respect to first support plate; and

a cavity plate positioned between the first support plate and the second support plate, the cavity plate having an aperture configured to accept only a protruding portion of the circuit package such that the protruding portion of the circuit package contacts the first support plate, and wherein the aperture is sized to create a peripheral void about only the protruding portion of the circuit package to permit a molding compound to be disposed thereabout.

16. (once amended) The system for molding a circuit package, as set forth in claim 1[15], wherein the aperture is the same height as the protruding portion of the circuit package.